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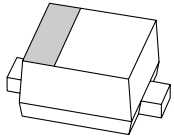
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# BAP50-02

General purpose PIN diode

Rev. 02 — 3 January 2008

Product data sheet

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NXP Semiconductors

# General purpose PIN diode

# BAP50-02

### FEATURES

- Low diode capacitance
- Low diode forward resistance.

### APPLICATIONS

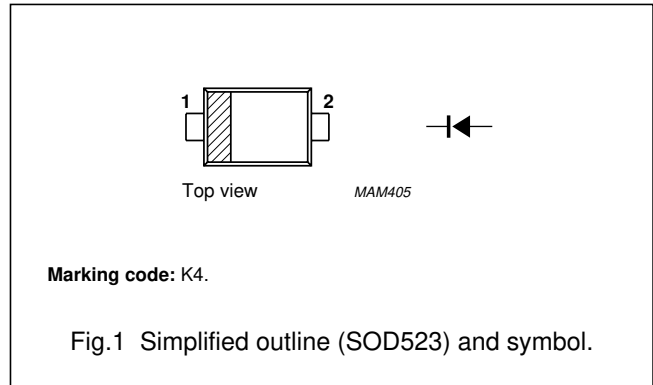
- General RF applications.

### DESCRIPTION

General purpose PIN diode in a SOD523 small SMD plastic package.

### PINNING

PIN	DESCRIPTION
1	cathode
2	anode



### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_R$	continuous reverse voltage		–	50	V
$I_F$	continuous forward current		–	50	mA
$P_{tot}$	total power dissipation	$T_s = 90\text{ °C}$	–	715	mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–65	+150	°C

## General purpose PIN diode

## BAP50-02

**ELECTRICAL CHARACTERISTICS**T<sub>j</sub> = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 50 mA	–	0.95	1.1	V
V <sub>R</sub>	reverse voltage	I <sub>R</sub> = 10 μA	50	–	–	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 50 V	–	–	100	nA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 0; f = 1 MHz	–	0.4	–	pF
		V <sub>R</sub> = 1 V; f = 1 MHz	–	0.3	0.55	pF
		V <sub>R</sub> = 5 V; f = 1 MHz	–	0.22	0.35	pF
r <sub>D</sub>	diode forward resistance	I <sub>F</sub> = 0.5 mA; f = 100 MHz; note 1	–	25	40	Ω
		I <sub>F</sub> = 1 mA; f = 100 MHz; note 1	–	14	25	Ω
		I <sub>F</sub> = 10 mA; f = 100 MHz; note 1	–	3	5	Ω
S <sub>21</sub>   <sup>2</sup>	isolation	V <sub>R</sub> = 0; f = 900 MHz	–	20.4	–	dB
		V <sub>R</sub> = 0; f = 1800 MHz	–	17.3	–	dB
		V <sub>R</sub> = 0; f = 2450 MHz	–	15.5	–	dB
S <sub>21</sub>   <sup>2</sup>	insertion loss	I <sub>F</sub> = 0.5 mA; f = 900 MHz	–	1.74	–	dB
		I <sub>F</sub> = 0.5 mA; f = 1800 MHz	–	1.79	–	dB
		I <sub>F</sub> = 0.5 mA; f = 2450 MHz	–	1.88	–	dB
S <sub>21</sub>   <sup>2</sup>	insertion loss	I <sub>F</sub> = 1 mA; f = 900 MHz	–	1.03	–	dB
		I <sub>F</sub> = 1 mA; f = 1800 MHz	–	1.09	–	dB
		I <sub>F</sub> = 1 mA; f = 2450 MHz	–	1.15	–	dB
S <sub>21</sub>   <sup>2</sup>	insertion loss	I <sub>F</sub> = 10 mA; f = 900 MHz	–	0.26	–	dB
		I <sub>F</sub> = 10 mA; f = 1800 MHz	–	0.32	–	dB
		I <sub>F</sub> = 10 mA; f = 2450 MHz	–	0.34	–	dB
τ <sub>L</sub>	charge carrier life time	when switched from I <sub>F</sub> = 10 mA to I <sub>R</sub> = 6 mA; R <sub>L</sub> = 100 Ω; measured at I <sub>R</sub> = 3 mA	–	1.05	–	μs
L <sub>S</sub>	series inductance	I <sub>F</sub> = 100 mA; f = 100 MHz	–	0.6	–	nH

**Note**

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

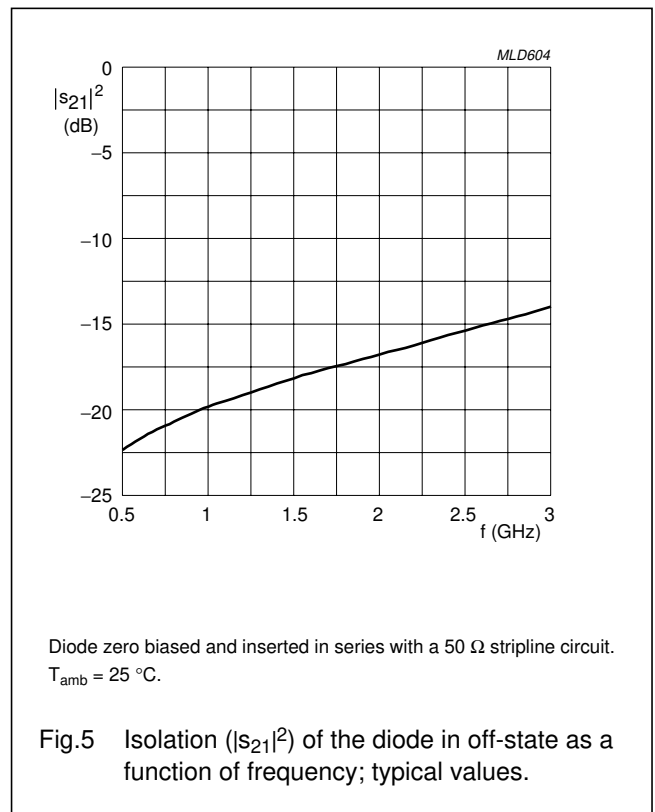
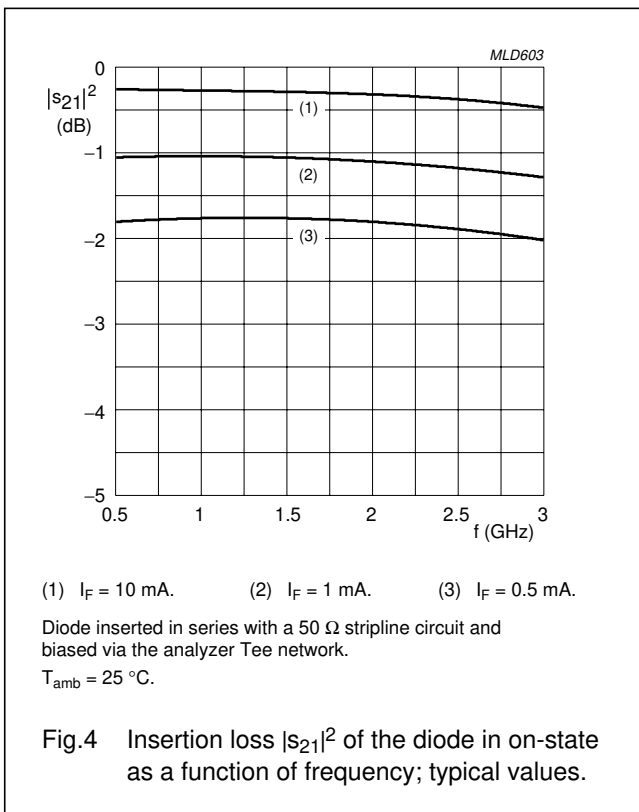
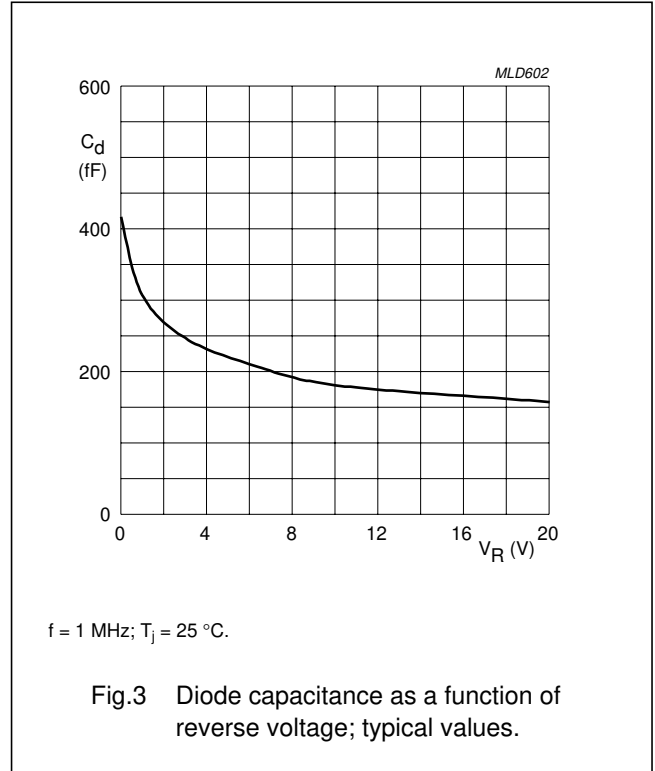
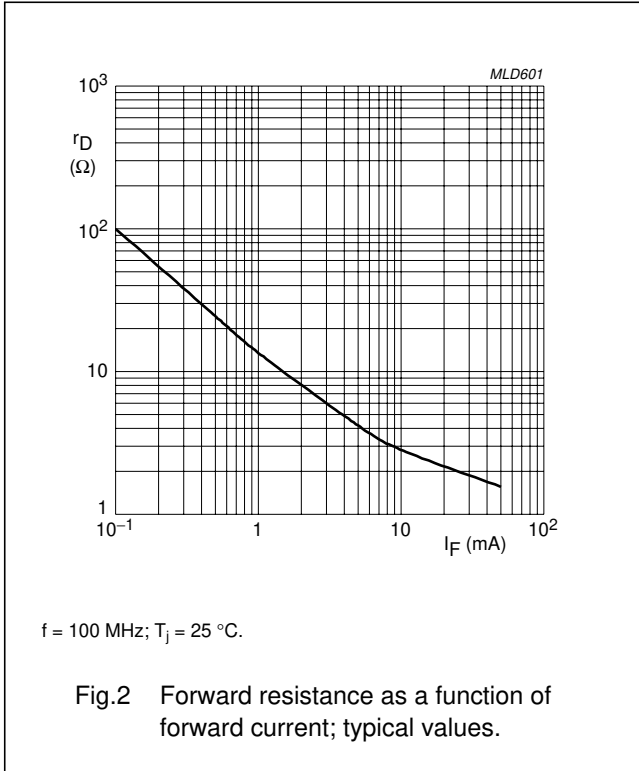
**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	85	K/W

General purpose PIN diode

BAP50-02

GRAPHICAL DATA



General purpose PIN diode

BAP50-02

PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD523

0 0.5 1 mm  
scale

**DIMENSIONS (mm are the original dimensions)**

UNIT	A	b <sub>p</sub>	c	D	E	H <sub>E</sub>	v
mm	0.65	0.34	0.17	1.25	0.85	1.65	0.1
	0.58	0.26	0.11	1.15	0.75	1.55	

**Note**  
1. The marking bar indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD523			SC-79			02-12-13-06-03-16

## Legal information

### Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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## Revision history

### Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP50-02_N_2	20080103	Product data sheet	-	BAP50-02_1
Modifications:	• Package outline drawing on page 5 changed			
BAP50-02_1 (9397 750 08113)	20010417	Product specification	-	-

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